AMENDMENTS

In the claims:

1. (Currently Amended) A printed wiring board comprising:

a printed wiring substrate having a plurality of wiring layers;

a thermal expansion buffering sheet integrally laminated on a surface of said printed wiring substrate and having a lower coefficient of thermal expansion than that of said printed wiring substrate; ~~and~~

a semiconductor device provided on the thermal expansion buffering sheet; and

an electrode pattern on a surface of said thermal expansion buffering sheet connecting the semiconductor device to a wiring section of said printed wiring board,

wherein the thermal expansion buffering sheet has a higher coefficient of thermal expansion than the semiconductor device.

2. (Original) A printed wiring board according to claim 1, wherein a coefficient of thermal expansion of said printed wiring substrate is 13 to 20 ppm, and a coefficient of thermal expansion of said thermal expansion buffering sheet is 6 to 12 ppm.

3. (Original) A printed wiring board according to claim 1, wherein said printed wiring substrate is a multi-layer wiring board which laminates wiring layers and insulation layers which are made of a glass cloth impregnated with an epoxy resin, alternately.

4. (Original) A printed wiring board according to claim 1, wherein said thermal expansion buffering sheet is made of an aramid.

5. Canceled

6. (Currently Amended) A printed wiring board according to claim ~~5~~1, wherein the semiconductor device is connected to said electrode pattern via a solder ball.

7. Canceled

8. (Previously Amended) A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately;

a thermal expansion buffering sheet integrally laminated on a surface of said multi-layer wiring section and having a lower coefficient of thermal expansion than that of said multi-layer wiring section;

a semiconductor device provided on the thermal expansion buffering sheet; and

an electrode pattern provided on a surface of said thermal expansion buffering sheet connecting the semiconductor device to the multi-layer wiring section,

wherein the thermal expansion buffering sheet has a higher coefficient of thermal expansion than the semiconductor device.

9. Canceled

10. (Previously Amended) A printed wiring board comprising:

a multi-layer wiring section which laminates wiring layers and insulation layers alternately;

a thermal expansion buffering sheet, a material of which is aramid, integrally laminated on a surface of said multi-layer wiring section and having a lower coefficient of thermal expansion than that of said multi-layer wiring section;

a semiconductor device provided on the thermal expansion buffering sheet; and

an electrode pattern provided on a surface of said thermal expansion buffering sheet connecting the semiconductor device to the multi-layer wiring section,

wherein the thermal expansion buffering sheet has a higher coefficient of thermal expansion than the semiconductor device.